

54Vout @ 2.5A

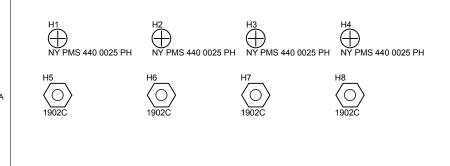
*NOTES:

1. Design is built on the PMP7896 RevB PCB.

Designed for: Public F		ise	Mod. Date: 4/9/2015		
Project Title: LM5122 Single-Phase Synchronous Boost					
Rev: A	Sheet Title: Schematic				
ntrol disabled	Assembly Variant: 001			et:1 of 2	115
	File: PMP9431 Schematics.SchDoc			Size: B	http://ww
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FID1 FID2 FID3

PCB Assembly PMP7896 RevB

В

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PCB LOGO Texas Instruments





Label Table Label Text Variant 001

ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

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ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	e Mod. D	ate: 4/9/2015	
TID #: PMP9431	Project Title: LM5122 Single-Phase Synchronous Boost			JI TEXAS
Number: PMP9431 Rev: A	Sheet Title: Hardware			TEXAS INSTRUMENTS
SVN Rev: Version control disabled	Assembly Variant: 001		Sheet: 2 of 2	institution
Drawn By:	File: PMP9431 TID Hardware.SchDoc		Size: B	http://www.ti.com
Engineer: Hrag Kasparian	Contact: http://www.ti.com/support		© Texas Instruments 2015	
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